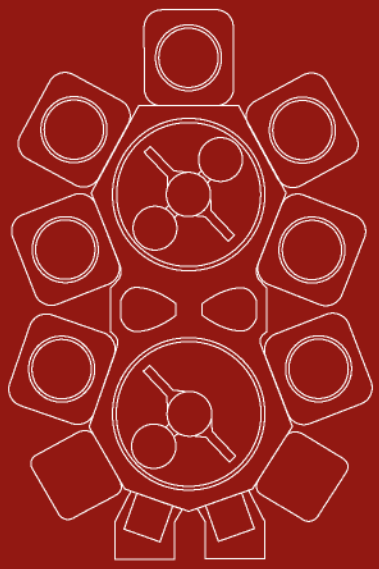
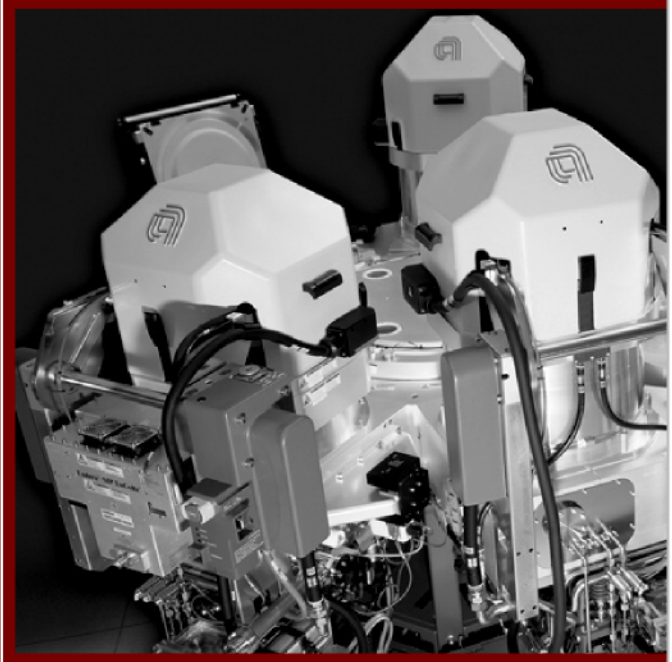
Exhibit 3

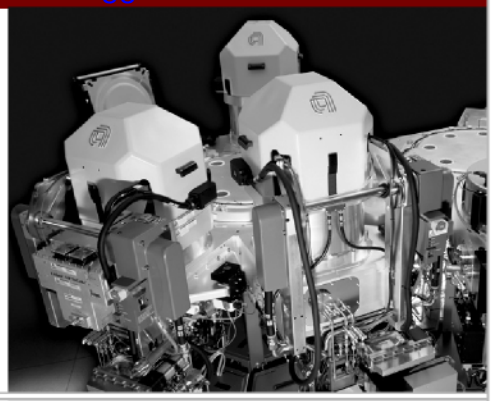
APPLIED ENDURA®/ENDURA2™

SYSTEM SPECIFICATIONS





With the innovative XP robots, optimized sequencing algorithms, and up to 7 process chambers, the Applied Endura®/Endura2™ 300mm achieves throughputs up to 80wph for Cu barrier/seed film deposition. Streamlined processes allow long target life and low consumable cost for improved cost of ownership and productivity.



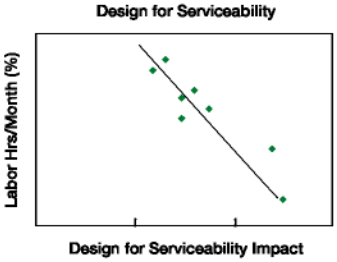
APPLIED ENDURA®/ENDURA2™ 300mm

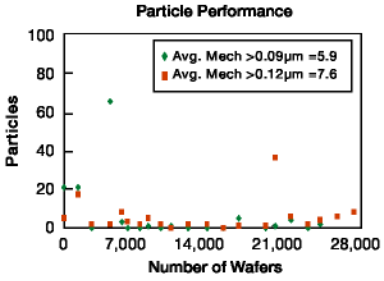
SYSTEM SPECIFICATIONS

With the innovative XP robot, optimized sequencing algorithms, and up to 7 process chambers, the Applied Endura®/Endura2™ 300mm achieves throughputs up to 80wph for Cu barrier/seed film deposition. Streamlined processes allow long target life and low consumable usage for improved cost of ownership and productivity. The Applied Endura/Endura2 300mm is built on the product-proven design of the Applied Endura 200mm, and has demonstrated consistent MTBF in excess of 250 hours and uptime over 85%. With the largest installed base for 300mm metal deposition, Applied Materials continues to leverage its extensive manufacturing experience to deliver a reliable, quality system.

The competitive demands of today's high volume semiconductor manufacturing environment require chip manufacturers to concentrate not only on technology, but also cost, productivity, and cycle time. It is essential for equipment to be rapidly integrated into production and, more importantly, to sustain high fab productivity with minimal tool downtime. Developed using advanced design analyses, and manufacturability models, the Applied Endura platform stands up to the challenge with its highly serviceable and highly reliable design.

Benchmark tool serviceability was designed in using a Design for Serviceability (DFS) approach. This development method ensures a simple and easy to service piece of equipment. A high DFS score correlates to fewer hours of tool downtime required for maintenance. The Endura2 earned a DFS score of 81, indicating that the design successfully incorporated lifecycle serviceability attributes.





FEATURES

- Cutting edge preclean and electrostatic chuck technologies
- Flexible process integration
- Extendible to 45nm and beyond
- Designed for serviceability, productivity and reliability

BENEFITS

- Throughput up to 80wph
- Long target life, low CoC
- Supports full range of metal deposition applications
- Enables excellent film quality and high device reliability

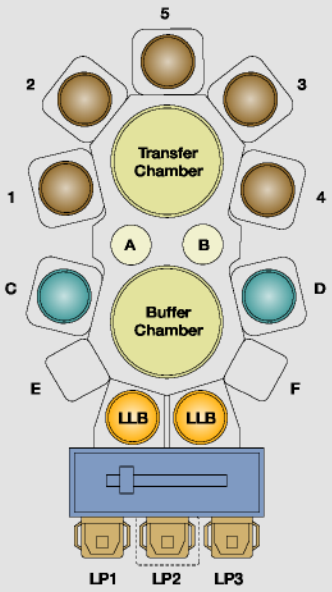
SYSTEM FEATURES

STANDARD CONFIGURATION	Number of Units	Position
Single wafer loadlock (SWLL)	2	LLA, LLB
Cooldown chamber	1	B
Buffer chamber	1	
Transfer chamber	1	
Factory interface (FI) with two load ports and integrated wafer aligner & mapping capability	1	

Note: Local Center Finder (LCF) available as retrofit on systems with VHP robots and cPCI

OPTIONAL CHAMBERS	Position
Third load port	5.3 FI
Degas chamber / Dual mode degas	E, F
Preclean (PC) chamber	C, D
PVD chamber	C, D, 1–5
CVD chamber	2, 3
ALD chamber	2, 3
Cooldown chamber	A, SWLLS

ENDURA CONFIGURATION



Process chambers	C, D, 1-5
Cooldown chambers	B
Degas chambers	E, F
Loadlocks	LLA, LLB
Factory interface	FI
Load port	LP 1-3

Endura advanced deposition process technology delivers a variety of materials and range of thicknesses from ultra-thin (<15Å) to thick films for conformal, fill and blanket deposition applications extendable to sub-65nm geometry requirements. The Applied Endura supports a wide range of metal deposition applications including Al, Cu barrier/seed, liner/barrier, advanced silicide, and UBM solutions. Combined with cutting-edge preclean and electrostatic chuck technologies, excellent film quality, high device reliability result. The architecture of the Applied Endura system enables multiple chamber (1-7) configurations supporting PVD, CVD and ALD technologies. Its modular design evolves with customer requirements to allow easy field upgrades to the latest technologies for extension of lifetime and investment value. Enhanced mainframe hardware provides excellent particle control and repeatable performance in a production-proven design.

HIGH THROUGHPUT FEATURES

- XP robot: four-axis, independent dual blade vacuum robot
- High speed chamber robotics
- Up to 7 process chambers
- Multiple temperature control options for heating and cooling wafers
- Motorized lifts at all chamber positions including C, D and degas

PROCESS AVAILABILITY

Listed below are the available standard processes. Additional process capability may be available.

Application	Chamber	
Cu Barrier/Seed	• SIP™EnCoRe Ta(N) • SIP EnCoRe Cu • SIP EnCoRe II Cu/TaN	• ALD TaN PC XT • Reactive PC XT
Al Interconnect	• Al • ALPS™ Al • SIP TTN	• Durasource® TTN • PC XT
Liner/Barrier	• IMP Ti • HP+ TxZ™ CVD TiN	• PC XT
Front End Metallization	• Standard Co • Standard Ni • ALPS Co	• ALPS Ni • PVD CleanW™ • PC XT
Back End Metallization (UBM/Bondpad)	• Standard PVD Cu • Standard PVD Ta(N) • Standard PVD Ti • Standard PVD Cu-Cr	• NiV • PC XT

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